

### General Description

The 4003 uses advanced trench technology to provide excellent RDS(ON). The device well suited for high current applications.

### Features

- P-Channel MOSFET
- Fast Switching
- Low ON-resistance
- 100% EAS Guaranteed
- RoHS Compliant

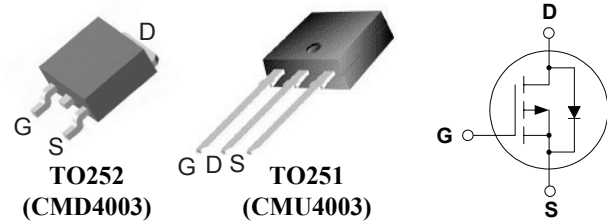
### Product Summary

BVDSS	RDSON	ID
-40V	20mΩ	-27A

### Applications

- DC/DC converters
- Inverter
- Power Supplies

### TO252 / TO251 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ C$	Continuous Drain Current <sup>1</sup>	-27	A
$I_D@T_C=100^\circ C$	Continuous Drain Current <sup>1</sup>	-21	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-54	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	64	mJ
$I_{AS}$	Avalanche Current	-27	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	35	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction -Case <sup>1</sup>	---	3.6	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub>=25°C , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-40	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-8A	---	14	20	mΩ
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-5A	---	18	28	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1	---	-2.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-32V, V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-32V, V <sub>GS</sub> =0V , T <sub>J</sub> =55 °C	---	---	-5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-10V , I <sub>D</sub> =-10A	---	17	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	2	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-20V, V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-1A	---	12	25	nC
Q <sub>gs</sub>	Gate-Source Charge		---	3.4	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	3.3	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-20V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω I <sub>D</sub> =-1A	---	24	---	ns
T <sub>r</sub>	Rise Time		---	15	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	60	---	
T <sub>f</sub>	Fall Time		---	8	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V , f=1MHz	---	2400	---	pF
C <sub>oss</sub>	Output Capacitance		---	180	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	105	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1 5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	-27	A
I <sub>SM</sub>	Pulsed Source Current <sup>2 5</sup>		---	---	-54	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1.6A , T <sub>J</sub> =25°C	---	---	-1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-20V,V<sub>GS</sub>=-10V,L=0.5mH,I<sub>AS</sub>=-17A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.